

ABSTRACT

A stacked chip-packaging structure consisting of a plurality of chip-packaging units is provided. Each of the chip-packaging units includes a substrate, a chip, a plurality of wires, a molding compound, and a plurality of solder balls. The chip-packaging units are, for example, of a BGA structure with high pin count, and are stacked up one over another and electrically connected through solder balls. With such structural features, the space that the stacked chip-packaging structure occupies is reduced and consequently the entire structure can be miniaturized.